PAN30TX06X

N-Ch 30V Fast Switching MOSFET

V_{DS}=30V, I_D=80A, $RDS_{(ON)}$=5.5mΩ

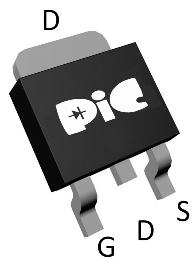
General Description

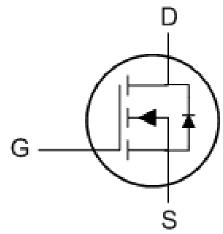
This PAN30TX06X N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

TO-252





Application

- Switch application
- DC/DC Converters Power
- Tools

Absolute Maximum Ratings

Parameter	Symbol	Rating		Units
		10s	Steady State	
Drain-Source Voltage	V_{DS}	30		V
Gate-Source Voltage	V_{GS}	±20		V
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_C=25℃	80		A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_C=100℃	57		A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_A=25℃	27	17	A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_A=70℃	23	14.5	A
Pulsed Drain Current[2]	I_{DM}	160		A
Single Pulse Avalanche Energy[3]	EAS	115.2		mJ
Avalanche Current	I_{AS}	48		A
Total Power Dissipation[4]	P_D@T_C=25℃	53		W
Total Power Dissipation[4]	P_D@T_A=25℃	6	2.4	W
Storage Temperature Range	T_{STG}	-55 to 175		℃
Operating Junction Temperature Range	T_J	-55 to 175		℃
Thermal Resistance Junction-ambient (Steady State)[1]	$R_{θJA}$	62		℃/W
Thermal Resistance Junction-Ambient [1] (t ≤10s)	$R_{θJA}$	25		℃/W
Thermal Resistance Junction-Case[1]	$R_{θJC}$	2.8		℃/W

Electrical Characteristics (T_J=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V , I_D=250uA	30	---	---	V
BVDSS Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to 25℃ , I_D=1mA	---	0.028	---	V/℃
Static Drain-Source On-Resistance[2]	$R_{DS(ON)}$	V_{GS}=10V , I_D=30A	---	4.7	5.5	mΩ
		V_{GS}=4.5V , I_D=15A	---	7.5	9	
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS} , I_D =250uA	1.0	1.5	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-6.16	---	mV/℃
Drain-Source Leakage Current	I_{DSS}	V_{DS}=24V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55℃	---	---	5	
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
Forward Transconductance	gfs	V_{DS}=5V , I_D=30A	---	22	---	S
Gate Resistance	R_g	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.7	3.4	Ω
Total Gate Charge (4.5V)	Q_g	V_{DS}=15V , V_{GS}=4.5V , I_D=15A	---	20	---	nC
Gate-Source Charge	Q_{gs}		---	7.6	---	
Gate-Drain Charge	Q_{gd}		---	7.2	---	
Turn-On Delay Time	$T_{d(on)}$	V_{DD}=15V , V_{GS}=10V , R_G=3.3Ω I_D=15A	---	7.8	---	ns
Rise Time	T_r		---	15	---	
Turn-Off Delay Time	$T_{d(off)}$		---	37.3	---	
Fall Time	T_f		---	10.6	---	
Input Capacitance	C_{iss}	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	2295	---	pF
Output Capacitance	C_{oss}		---	267	---	
Reverse Transfer Capacitance	C_{rss}		---	210	---	

Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current[1,5]	I_S	V_G=V_D=0V , Force Current	---	---	80	A
Pulsed Source Current[2,5]	I_{SM}		---	---	160	A
Diode Forward Voltage[2]	V_{SD}	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
Reverse Recovery Time	t_{rr}	IF=30A , dI/dt=100A/µs , T_J=25℃	---	14	---	nS
Reverse Recovery Charge	Q_{rr}		---	5	---	nC

Note :
1.Pulse width limited by maximum junction temperature.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=53.8A
4.Ensure that the channel temperature does not exceed 150°C.
5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

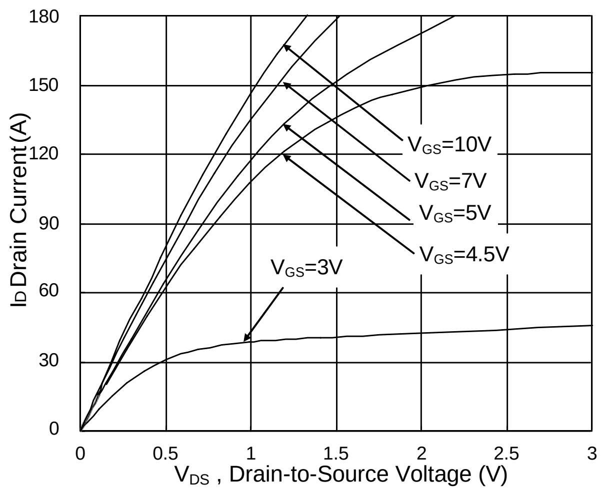


Fig.1 Typical Output Characteristics

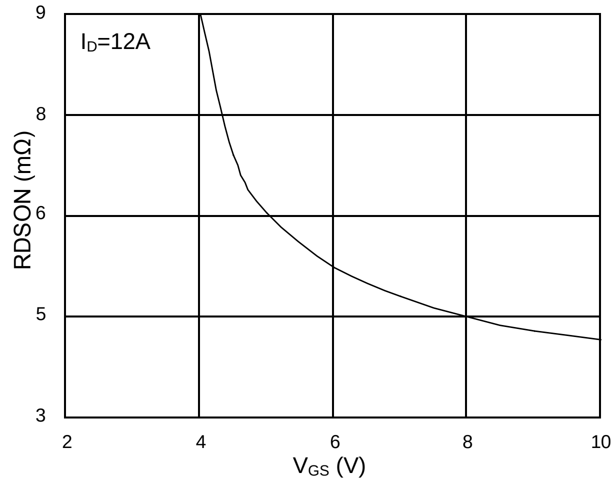


Fig.2 On-Resistance vs. G-S Voltage

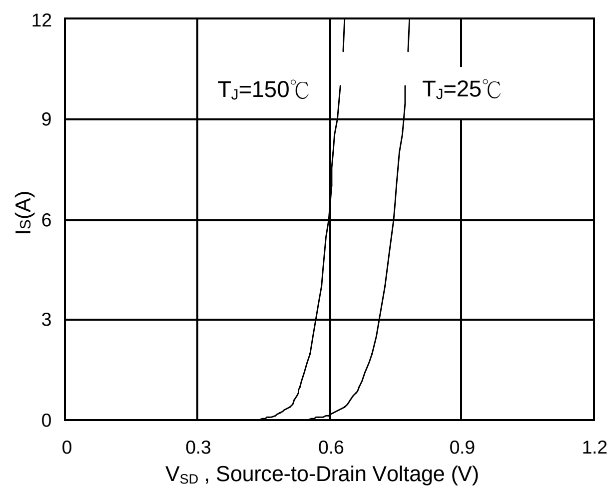


Fig.3 Forward Characteristics of Reverse

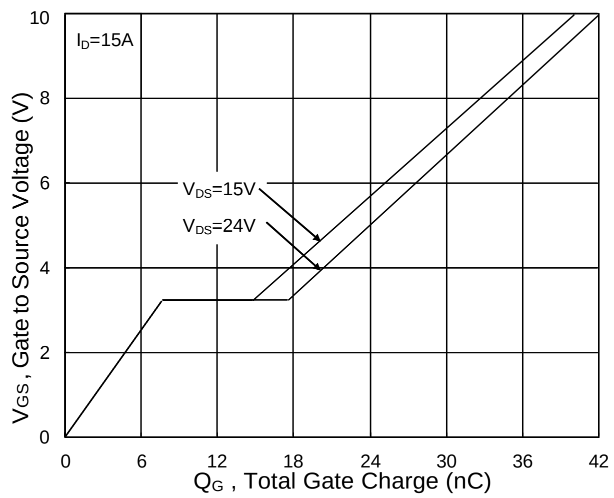


Fig.4 Gate-Charge Characteristics

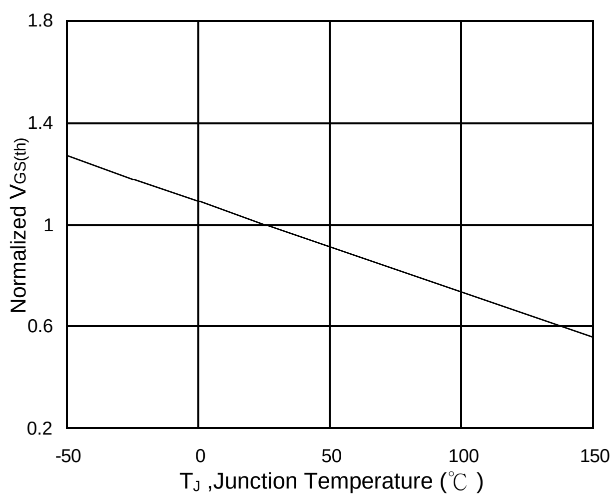


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

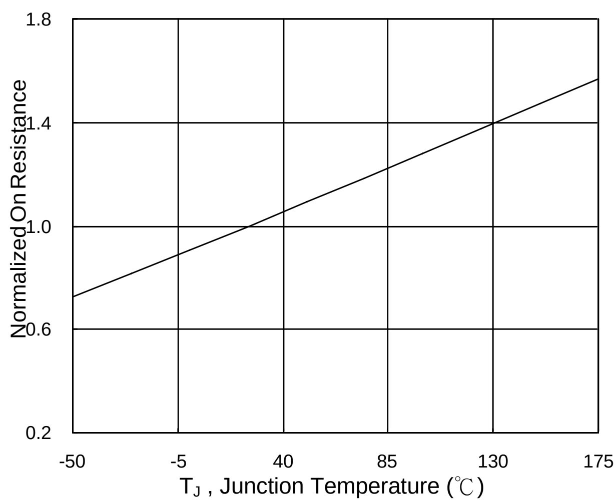


Fig.6 Normalized R_{DSON} vs. T_J

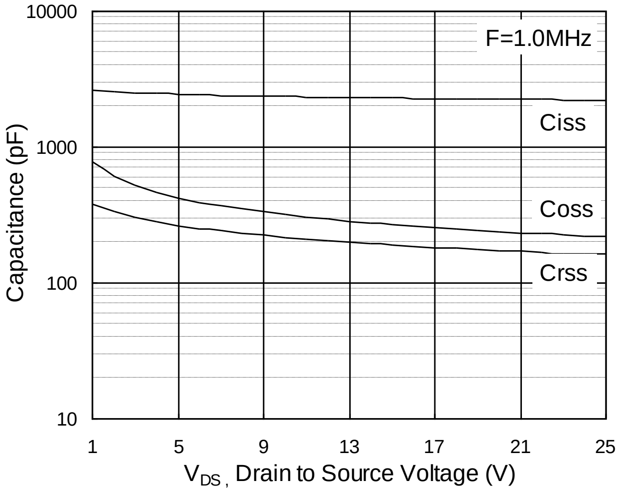


Fig.7 Capacitance

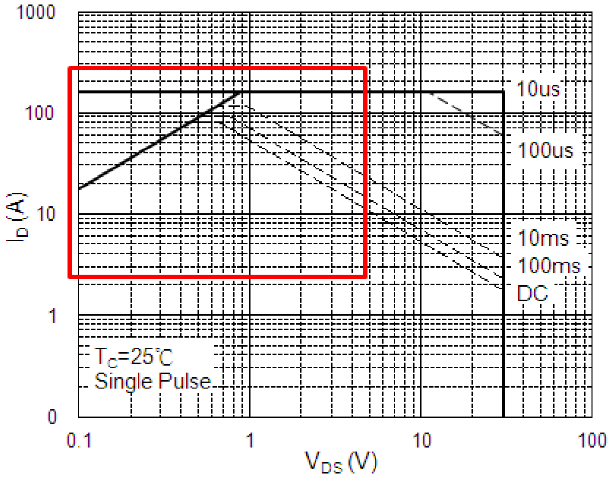


Fig.8 Safe Operating Area

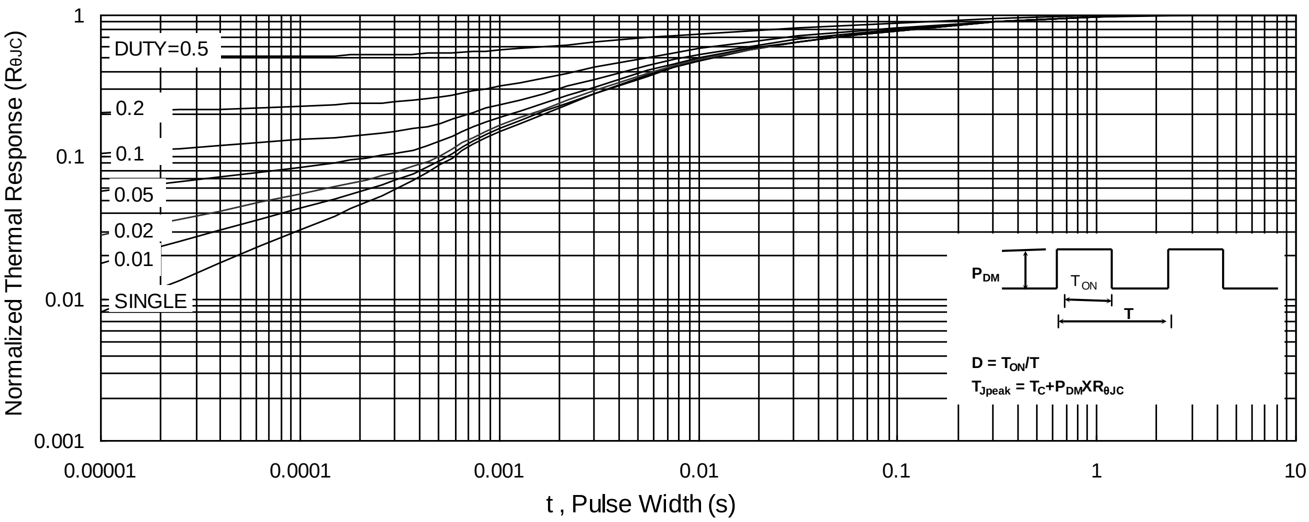


Fig.9 Normalized Maximum Transient Thermal Impedance

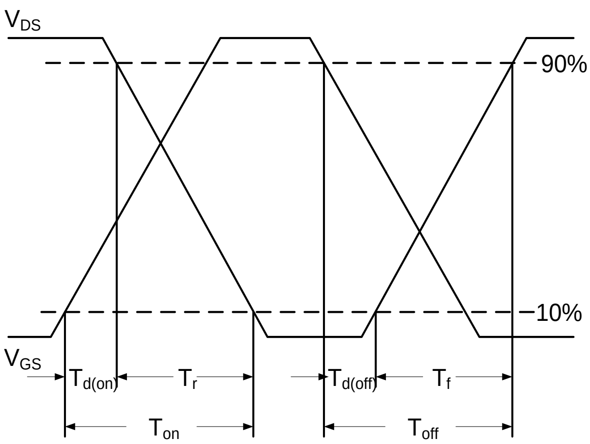


Fig.10 Switching Time Waveform

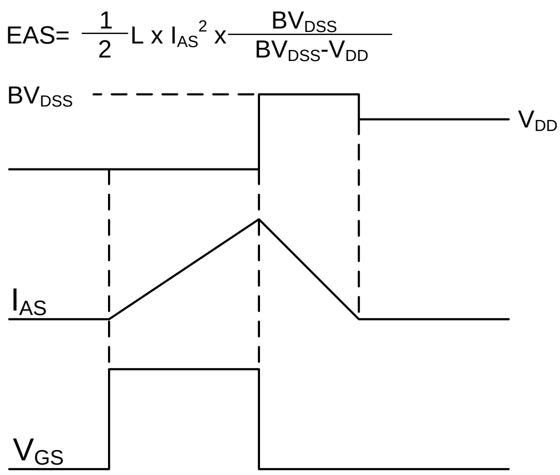
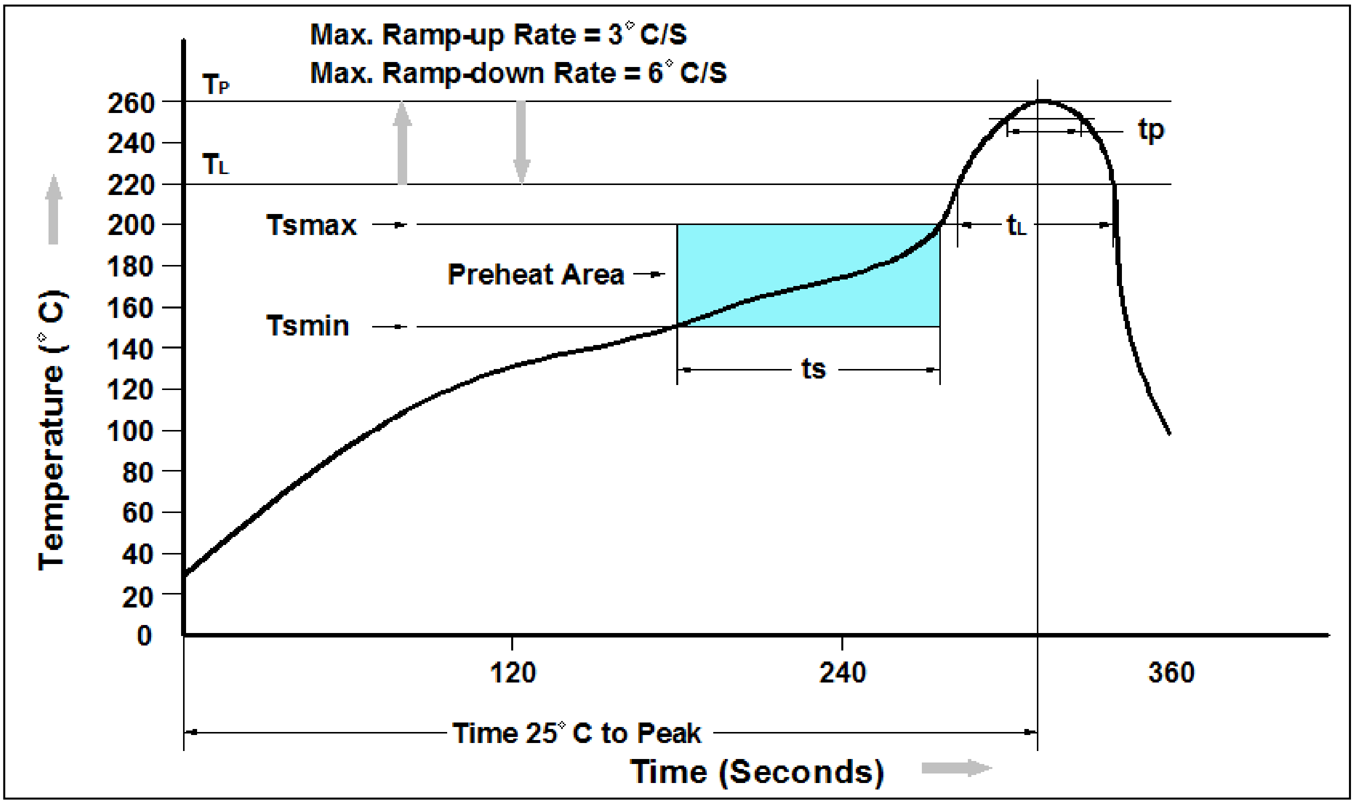


Fig.11 Unclamped Inductive Switching Waveform

Recommand IR Reflow Soldering Thermal Profile

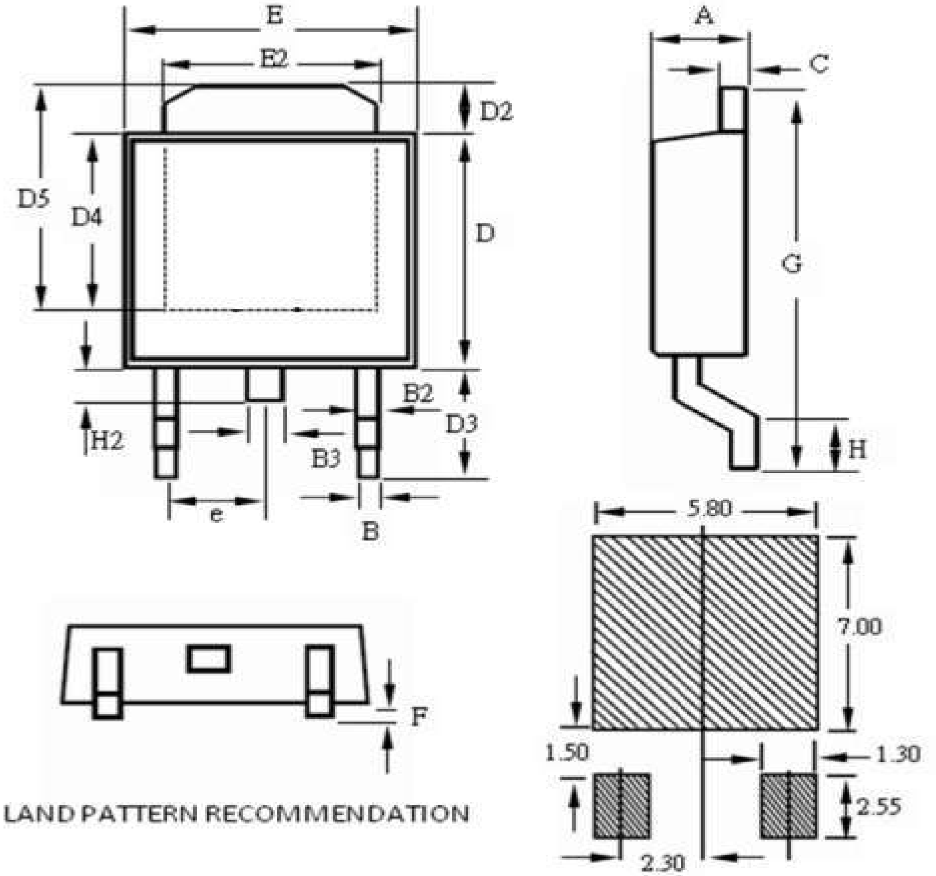


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

Ordering Information

Part Number	Description	Quantity
PAN30TX06X	TO-252 Reel	2500 pcs

➢ Package Information (TO-252)



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.10	--	2.50	0.083	--	0.098
B	0.30	--	0.89	0.012	--	0.035
B2	0.40	--	1.14	0.016	--	0.045
B3	0.60	--	1.00	0.024	--	0.039
C	0.40	--	0.89	0.016	--	0.035
D	5.30	--	6.25	0.209	--	0.246
D2	0.50	--	1.70	0.020	--	0.067
D3	2.20	--	3.40	0.087	--	0.134
D4	4.32	--	--	0.170	--	--
D5	5.21	--	--	0.205	--	--
E	6.30	--	6.73	0.248	--	0.265
E2	4.80	--	5.46	0.189	--	0.215
F	0.00	--	0.30	0.000	--	0.012
G	9.20	--	10.41	0.362	--	0.410
H	0.90	--	1.95	0.035	--	0.077
H2	0.50	--	1.10	0.020	--	0.043
e	--	2.30	--	--	0.091	--

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